

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	MDG/19/11504	
1.3 Title of PCI	ST Shenzhen (China) additional source of Carrier Tape and Cover Tape for TSSOP 20 package products	
1.4 Product Category	All products in TSSOP20L from ST Shenzhen	
1.5 Issue date	2019-06-07	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Wafer Fab (Consumables)	Packing: new supplier for customer deliveries	SH1T---ST SHENZHEN -CHINA

4. Description of change

	Old	New
4.1 Description	single source 3M carrier tape and 3M cover tape	first source 3M carrier Tape and 3M cover tape Second source CPAK carrier tape and CPAK cover tape
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	- Form: no change on the product, visual aspect change of the Carrier Tape and Cover Tape. - Fit: no change	

5. Reason / motivation for change

5.1 Motivation	To multiply the source to reduce line down risks.
5.2 Customer Benefit	LOGISTICS IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Not Applicable
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7. Timing / schedule

7.1 Date of qualification results	2019-05-29
7.2 Intended start of delivery	2019-05-29
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

11504 Public product.pdf
11504 PCi11504 Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F030F4P6	
	STM32F030F4P6TR	
	STM32F031F4P6	
	STM32F031F4P6TR	
	STM32F031F4P7	
	STM32F031F6P6	
	STM32F031F6P6TR	
	STM32F031F6P7	
	STM32F031F6P7TR	
	STM32F038F6P6	
	STM32F038F6P6TR	
	STM32F070F6P6	
	STM8L051F3P6	
	STM8S003F3P6	
	STM8S003F3P6TR	
	STM8S103F2P3	
	STM8S103F2P3TR	
	STM8S103F2P6	
	STM8S103F2P6TR	
	STM8S103F3P3	
	STM8S103F3P3TR	
	STM8S103F3P6	
	STM8S103F3P6TR	
	STM8S903F3P3	
	STM8S903F3P6	
	STM8S903F3P6TR	
	STM8SPLNB1P6	

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ST Shenzhen (China)
**additional source of Carrier Tape and Cover Tape
for TSSOP 20 package products**

MDG - Microcontrollers Division (MCD)

What are the changes?

Changes described in the below table:

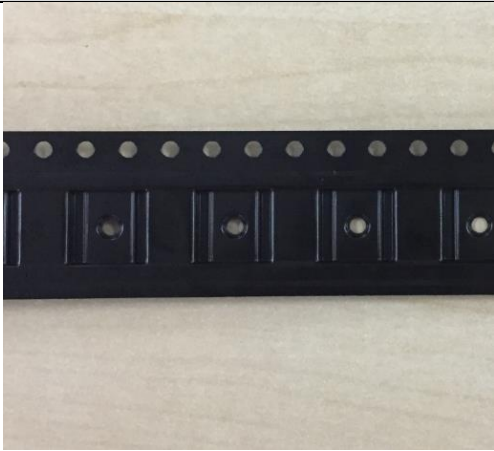
	Current source	Added source
CARRIER TAPE	3M	CPAK
COVER TAPE	3M	CPAK

No FIT change, no need to change manufacturing set-up at customer premises.
Dimension remains within spec and follows international standards EIA 481 (US) / IEC 60286-3 (EU).

No functional change, No quality difference

How can the change be seen?

Carrier Tape and cover Tape may have different visual aspect. See table below.

	Current source 3M Has a glossy finishing	Added source CPAK Has a dull, matt finishing
TAPE	 	 
COVER TAPE		



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : ST Shenzhen (China) additional source of Carrier Tape and Cover Tape for TSSOP 20 package products

PCI Reference : MDG/19/11504

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32F030F4P6	STM32F031F6P6	STM32F031F6P7
STM32F030F4P6TR	STM8S103F3P3TR	STM32F031F4P7
STM32F031F6P7TR	STM8S003F3P6	STM8S103F2P6
STM8S103F2P3	STM32F070F6P6	STM8S903F3P6TR
STM8S903F3P6	STM32F031F4P6TR	STM32F031F6P6TR
STM32F038F6P6TR	STM8L051F3P6	STM8S103F3P3
STM8S103F3P6TR	STM32F031F4P6	STM8S903F3P3
STM32F038F6P6	STM8S103F3P6	STM8S003F3P6TR
STM8S103F2P6TR	STM8SPLNB1P6	STM8S103F2P3TR



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